

No. KSD-248-0108-1

## TECHNICAL SHEET

KYOCERA CORPORATION  
SEMICONDUCTOR PARTS DIVISION4  
SEALANT DIVISION

SEALANT NCO-150H

## 1 Physical Property

Item	Unit	Data
Color		Translucence
Specific Gravity		1.7
* Shear Strength	MPa	26.48
Coefficient of Thermal Expansion	$1/^\circ\text{C} \times 10^{-6}$	7
Glass Transition Point	$^\circ\text{C}$	160
Water Absorption	%	—
Dielectric Constant	$\epsilon(1\text{MHz})$	6
Loss Factor	$\tan\delta(1\text{MHz})$	0.03
Thermal Conductivity	W/m·K	—
Surface Resistivity	$\Omega$	$1.0 \times 10^{14}$

Note \* Curing Sample : Ceramic / Ceramic

## 2 Reliability [Judgment : MIL-STD 883D 1014]

Test Item	MIL-STD 883D	Condition	NG:N=100
Temperature Cycle	1010-COND C	-85 $^\circ\text{C}$ -150 $^\circ\text{C}$ 40Cycles	0/100
Thermal Shock	1011-COND A	0 $^\circ\text{C}$ -100 $^\circ\text{C}$ 40Cycles	0/100
Impact Resistance	2002-COND B	1500G, 0.5M, 5Times	0/100
High Temp Storage	1008-COND C	150 $^\circ\text{C}$ /1000H	0/100
Low Temp Storage		-85 $^\circ\text{C}$ /1000H	0/100
High Temp & Humidity		85 $^\circ\text{C}$ , 85%RH, 1000H	0/100
Pressure Cooker		121 $^\circ\text{C}$ , 0.21MPa, 50H	0/100

Note Ceramic Curing(.708 inch SQ ; Sealing Width.040 inch)